PROCEDURE FOR SOLVENT CLEANING OF SILICON WAFERS

1. Put the wafer on top of the chuck of the spin coater located in the fume hood wet bench.

2. Check recipe conditions for:
   a. Spin speed range between 3000 and 4000rpm
   b. Total time of 8 mins

3. Pour Acetone on the rotating wafer and use foam-cotton swab to remove gently any residues during 1 min. Do not stop pouring acetone during this lapse of time.

4. Pour methanol on the rotating wafer and use foam-cotton swab to remove gently any residues during 1 min. Do not stop pouring methanol during this lapse of time.

5. Pour isopropyl alcohol on the rotating wafer and use foam-cotton swab to remove gently any residues during 1 min. Do not stop pouring the solvent during this lapse of time.

6. Rinse wafer with DI water during 1 min.

7. Blow dry the wafer with nitrogen during 1 min.

8. Turn the vacuum off of the spinner and proceed to remove the wafer from the chuck using tweezers to avoid touching the cleaned surface.